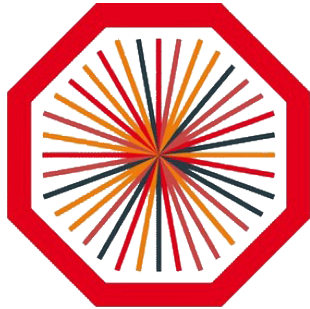
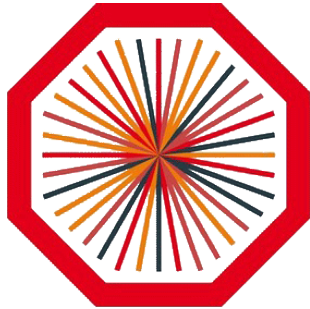


ALICE



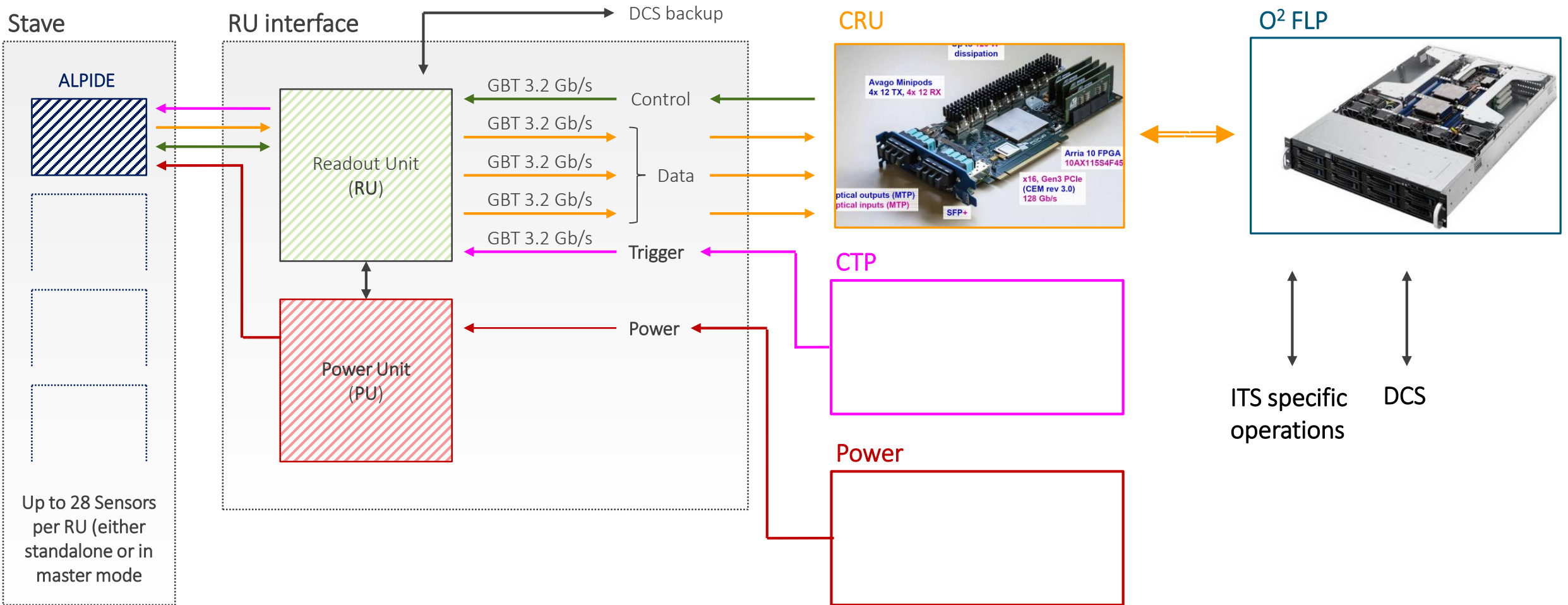
**Readout Electronics
& Power Distribution**



Power distribution

Power – Brief recall to ITS Readout Units and Power Board system

- The ITS front-end electronic is divided into modular Readout Units (RU), identical for each layer.
- Each readout unit controls an entire stave, including power to the sensors (through custom-made power units).
- The CRU interfaces with the Readout Unit only, which in turn manages the trigger and the power for the stave.



Power – components production status

Power and Bias buses

- Production appears to be proceeding according to schedule. Minor issues have been addressed.

OL-FBs and ML-FBs production status

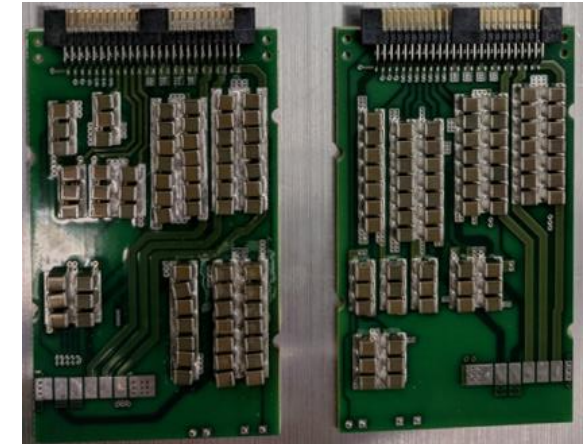
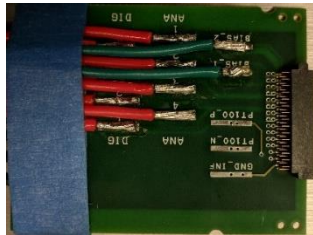
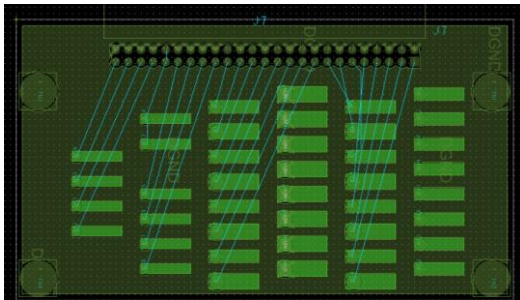
- The full production of FB is now completed and shipped to Torino.

OL-FB-BOBs, ML-FB-BOBs and PB-BOBs production status

- The full production of BOBs have been delivered to LBNL and shipped to CERN for assembly into cable harnesses. The assembly is in process at Fisher.

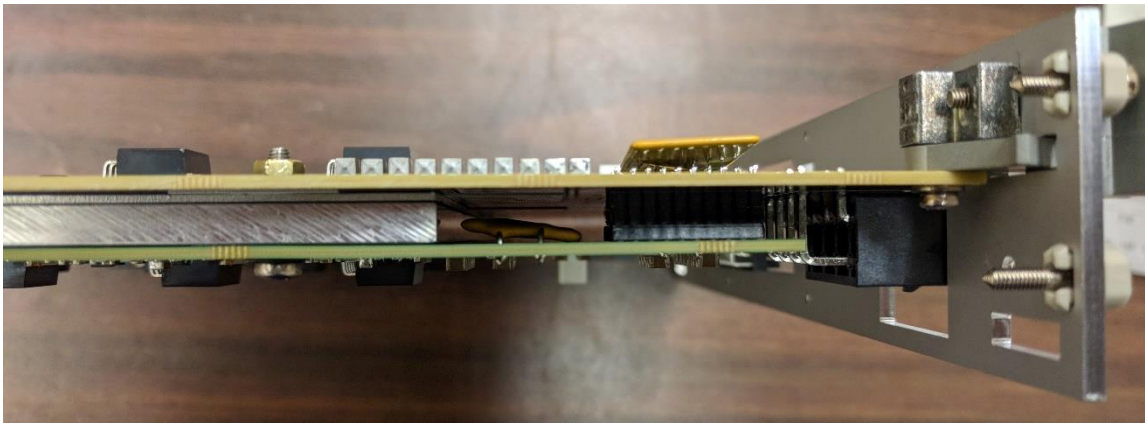
PB-BOB brackets

- PB BOB brackets have been ordered and should arrive in the next few weeks.



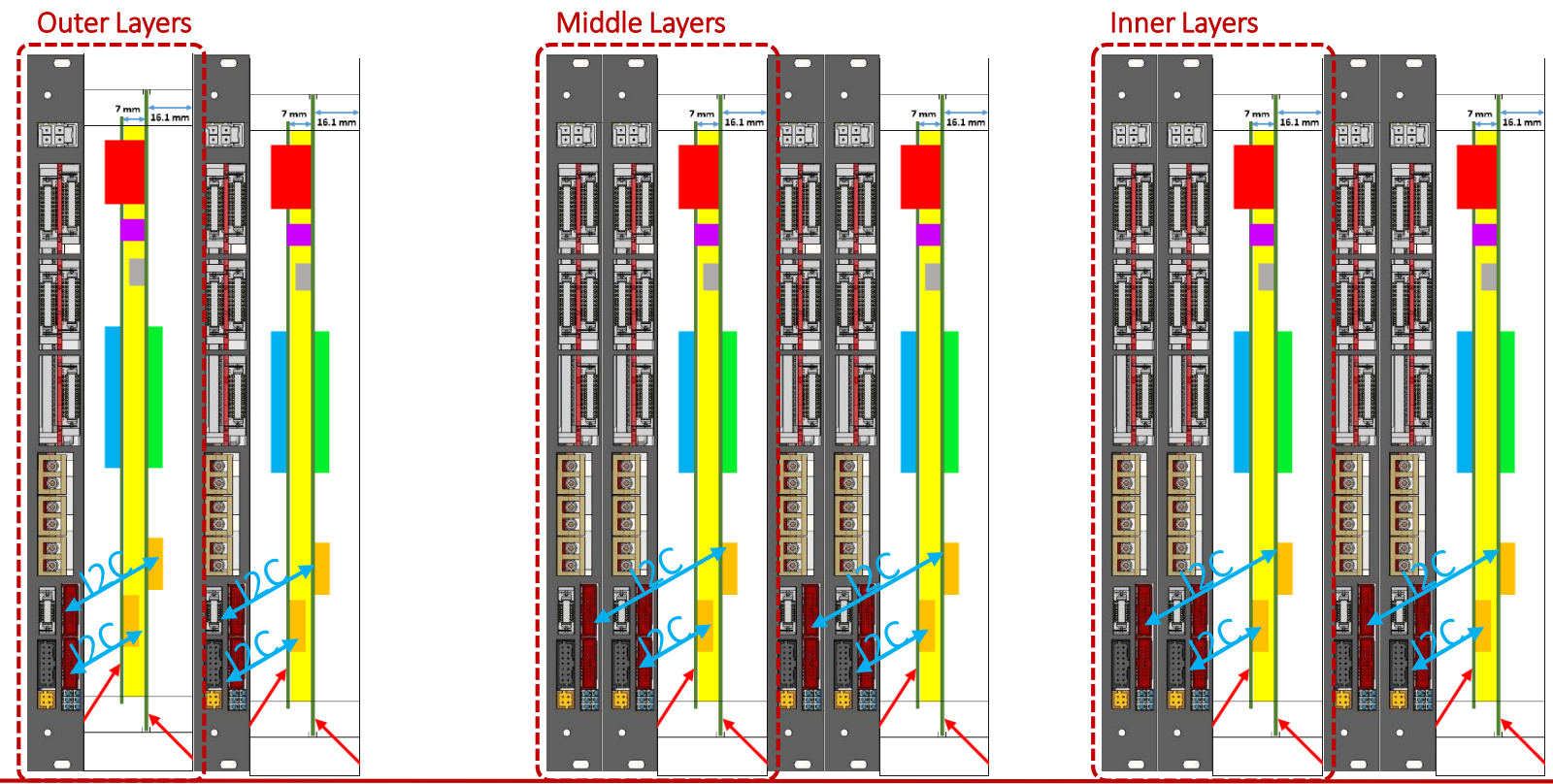
Power – LBNL power board production status

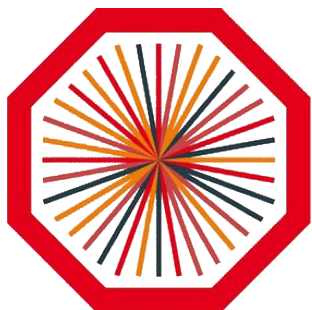
- 24 assembled and tested power boards shipped to CERN with CERN produced heat exchangers.
- 5 assembled and tested power boards shipped CERN with heat exchangers from the vendor
- The heat exchangers from the vendor have a smaller ID tubing than was specified. Approximately 1-1.2 mm.
- We will be making tests at LBNL to see the temperature rise as a function of flow pressure (remember we have a negative pressure water system so we do not have a lot of pressure headroom).



Power – 150 CERN purchased Power Boards production status

- We have been in contact with the vendor for parts substitution and PCB parameter adjustments. A supplementary cost has been established for these changes and the purchase order has been placed by CERN.
- There will be a delay associated with this set of changes and the 5 pre-series power boards should be delivered in approximately 3 weeks.
- If all goes as planned, the pre-series PBs of this batch will arrive at CERN in early November 2018, the first delivery of 73 will be at CERN in March 2019 and the balance of 72 will be at CERN by June 2019.

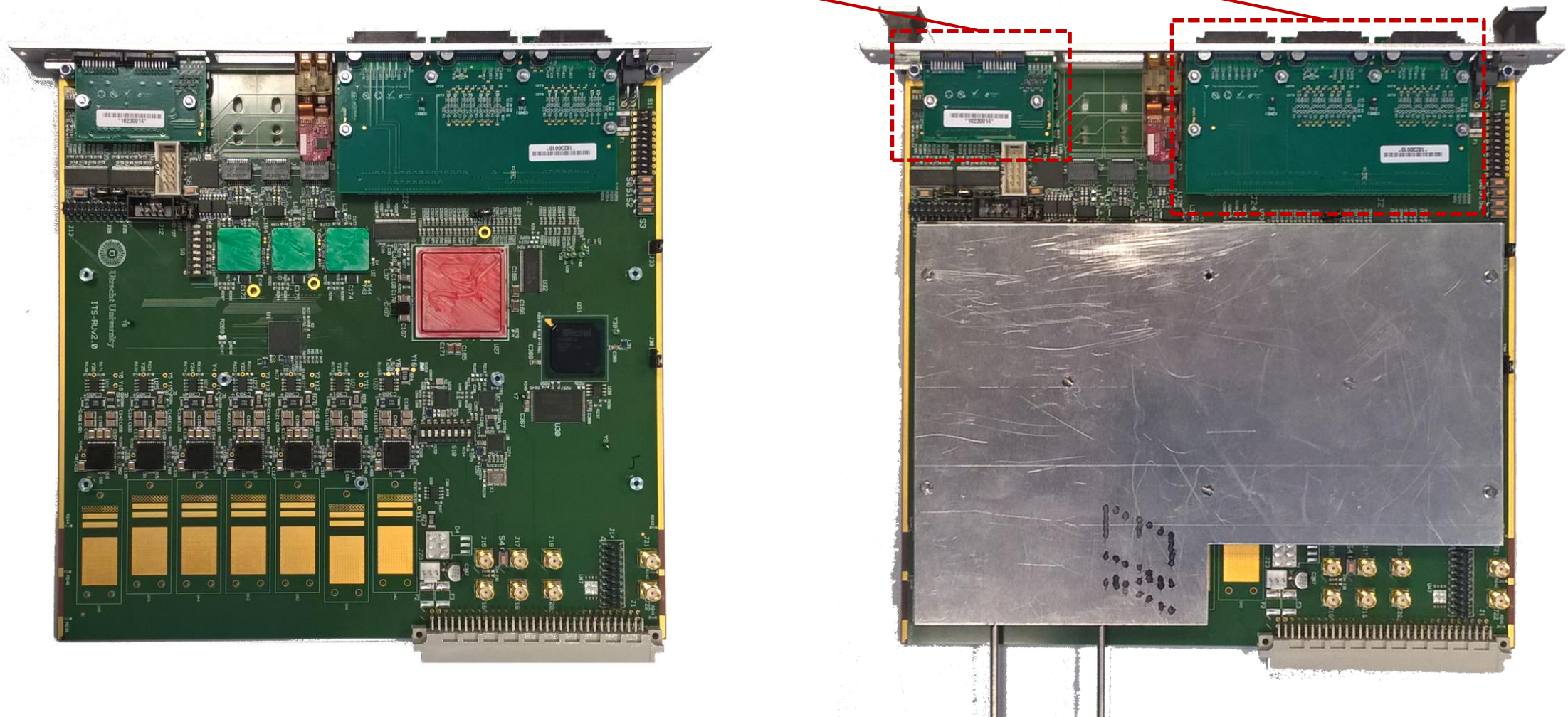




Readout Unit

Readout Unit – Design is in production (official version is RU2v1)

- RU2v1 is in production as today (could have been completed by the time of this talk).
- 1 bare PCBs arrived at CERN: visual inspection ok, now being cut for inner layers quality verification.
- All daughter boards arrived from Austin: 218 Power Mezzanines and 218 Transition Boards



Readout Unit – Production schedule

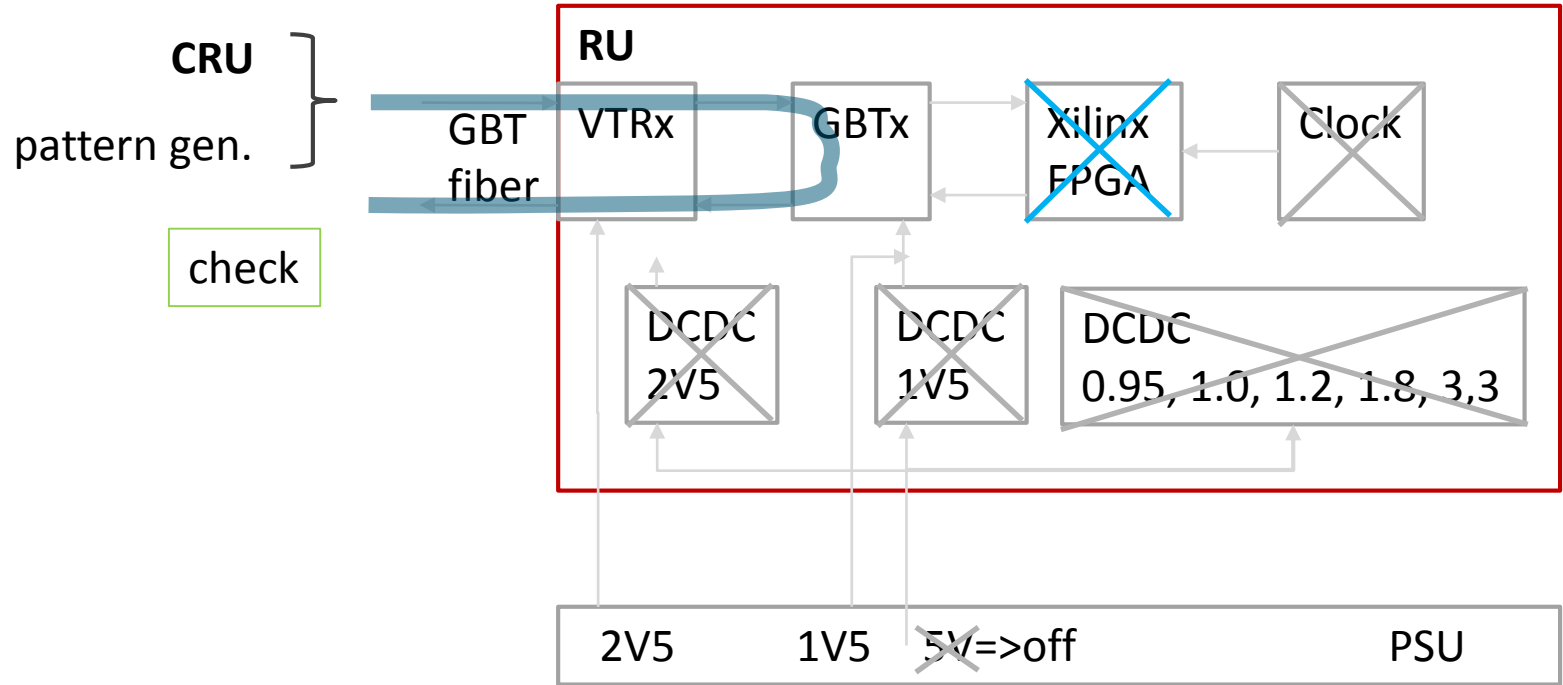
- First 20 board expected by November 21-24 (this week!).

Production schedule (confirmed)

Phase		Qty	Week	Due
Purchase Order	T0			14 Sept 2018
Pre-series delivery	T0 + 10w	20 (4 MFT)	47	21 Nov 2018
Acceptance of pre-series	T0 + 13w	20 (4 MFT)	48, 49, 50	14 Dec 2018
Batch 1 delivery	T0 + 22w	140 (36 MFT)	7	15 Feb 2019
Batch 2 delivery	T0 + 29w	150 (48 MFT)	14	5 apr 2019

Readout Unit – Issue under investigation

- Erratic instability produces GBT link error (few per hours) on some boards, but sometimes it disappear.
- So far defeated any debugging, tests ongoing + GBT team help.



- All DCDC off, external supply on 1V5 rail & 2V5 directly to VTRx, errors remain
- Also fiber and VTRx were replaced=>
- Found using standard CRU (but could be in GBT FPGA).

Readout Unit – Testing system ready

- Full test suite (hardware/firmware/software) ready in Utrecht/Nikhef

Testing / quality control:

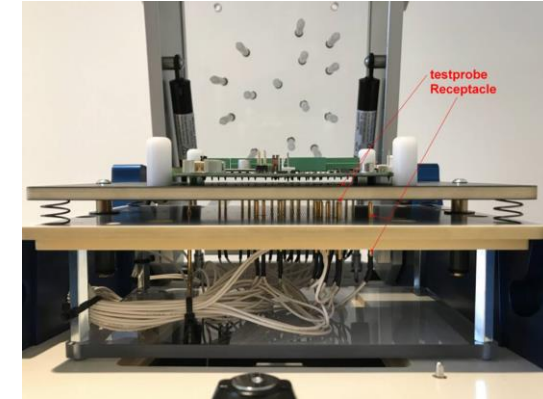
- Producer: PCB electrical test, characteristic impedance, mechanical cross sections
- Detailed visual inspection on a sub-sample of boards (CERN)
- Boards sent to Utrecht/Nikef for acceptance.

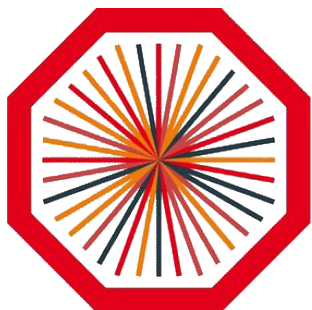
Standard acceptance testing (on all boards) – very short summary here.

- Scan barcode (bought/tested scanner)
- Power-on test (Impedance check for shorts, power rail voltages and currents).
- Program USB3 I2C PROMs, GBTx, check if all 3 GBTx are visible
- Loopback tests (Transceivers, GBT)
- All firmware(s) upload and testing (XCKU060, PA3, Xilinx DNA)
- Read and store Flash bad blocks

Extensive testing (on sub-set):

- Multiple power on power off sequences (HAMEG HMP4040 PC controlled PSU)
- Test in climate chamber NIKHEF climate chamber (reserved FOR wk48-53)
 - Passive: multiple cycles 0°C (noncondensing) to 80°C





Data cables

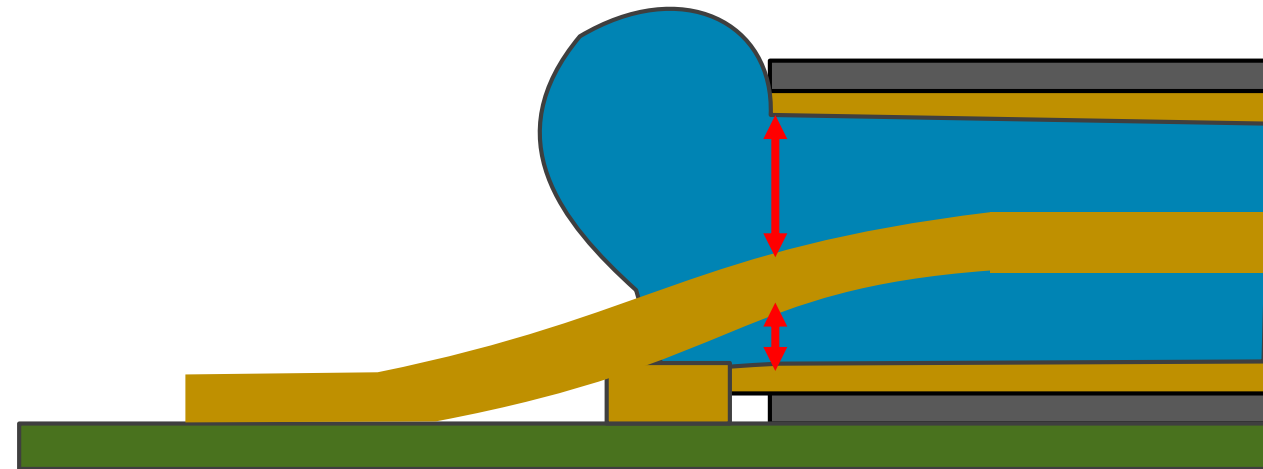
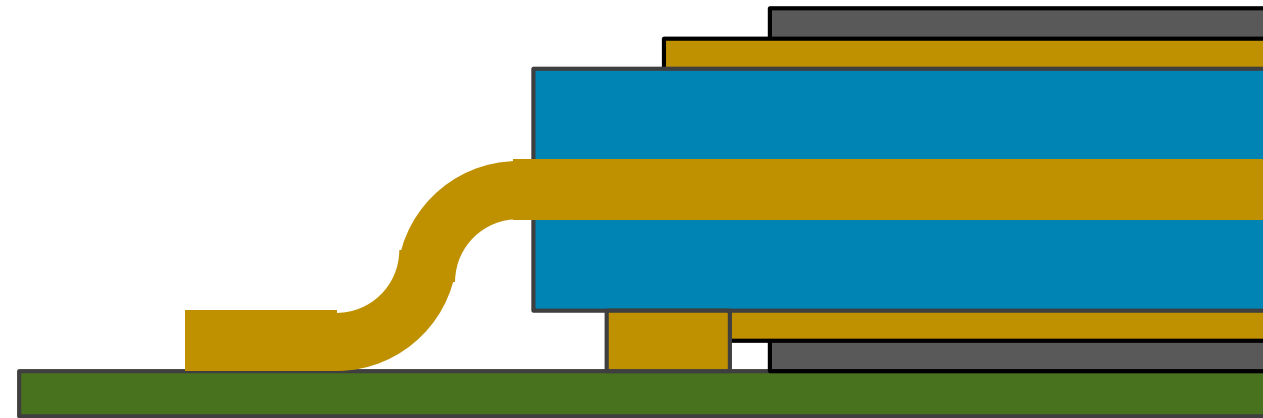
Data cables – Issue overview

Overview

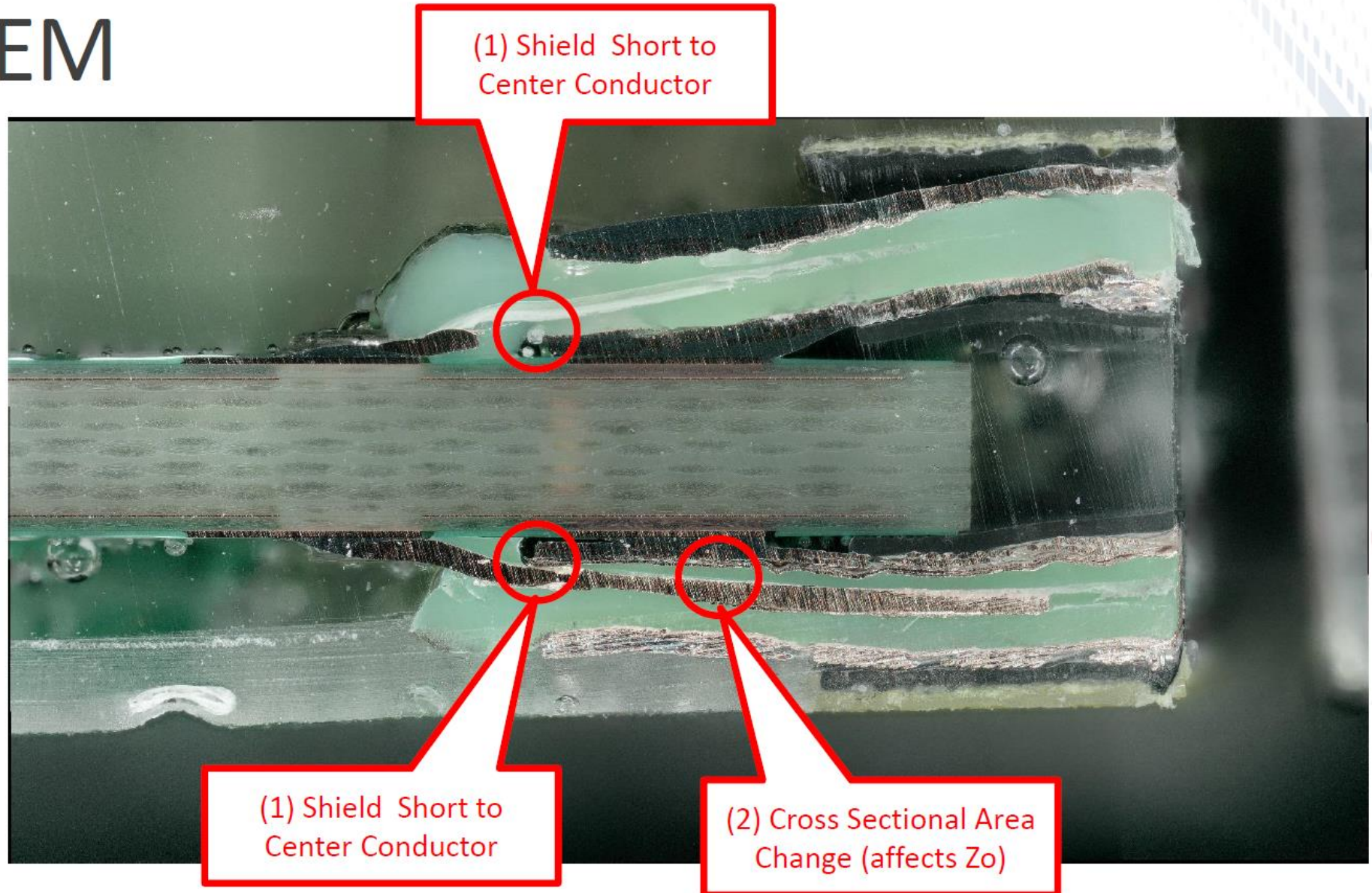
- Samtec committed 2 engineers (US based) full time on our cables, with the further support of a production expert and a project manager (Jason). Total team size is 5, with 2 full-time members.
- Material taken to the meeting was very good, clearly illustrating the status of the process development and the problems encountered so far: it seems they put resources on the task.

The issue in prototypes production

- Melting of the custom made dielectric while soldering the cable to the PCB, as it has lower melting point respect the standard one, which:
 - 1) may short the central conductor with the shielding,
 - 2) even if no short happens, the change in geometry (extreme in the first prototypes) affects the z_0 of the cable

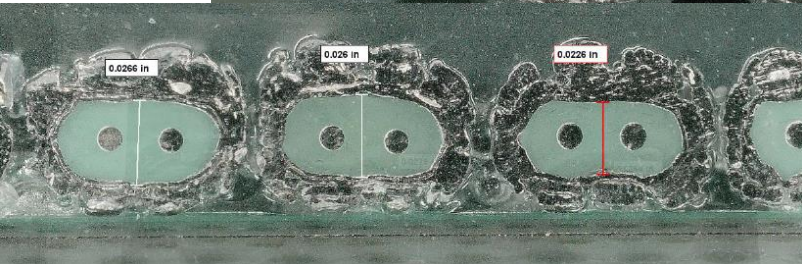
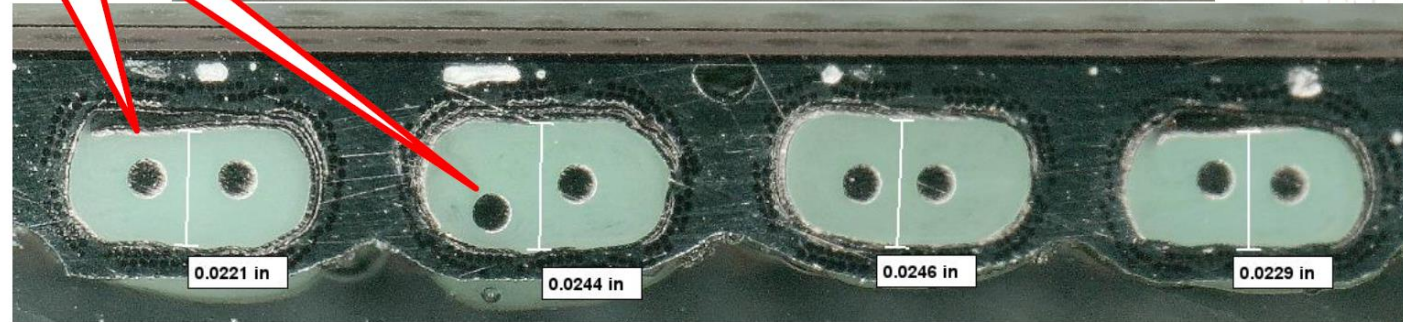
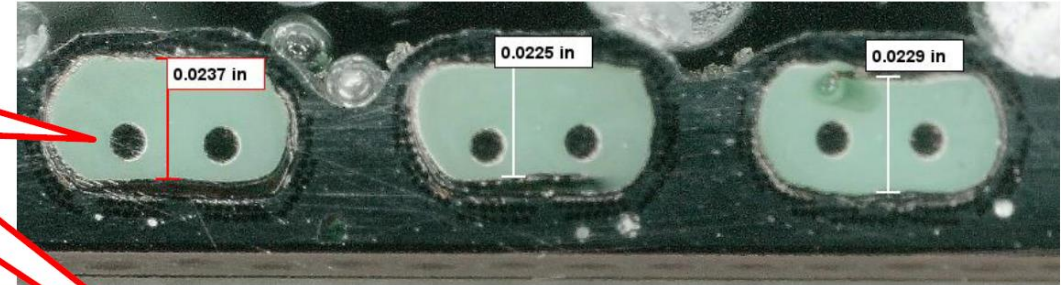
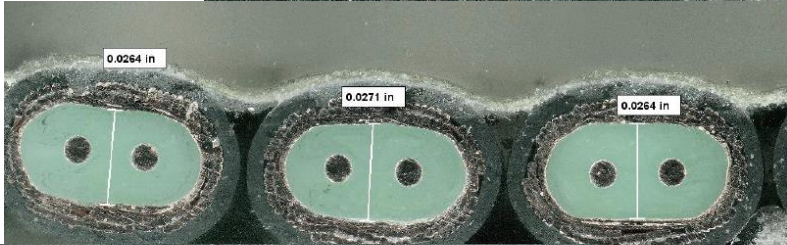
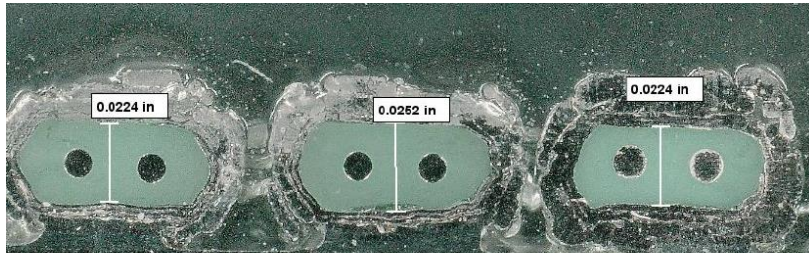


PROBLEM



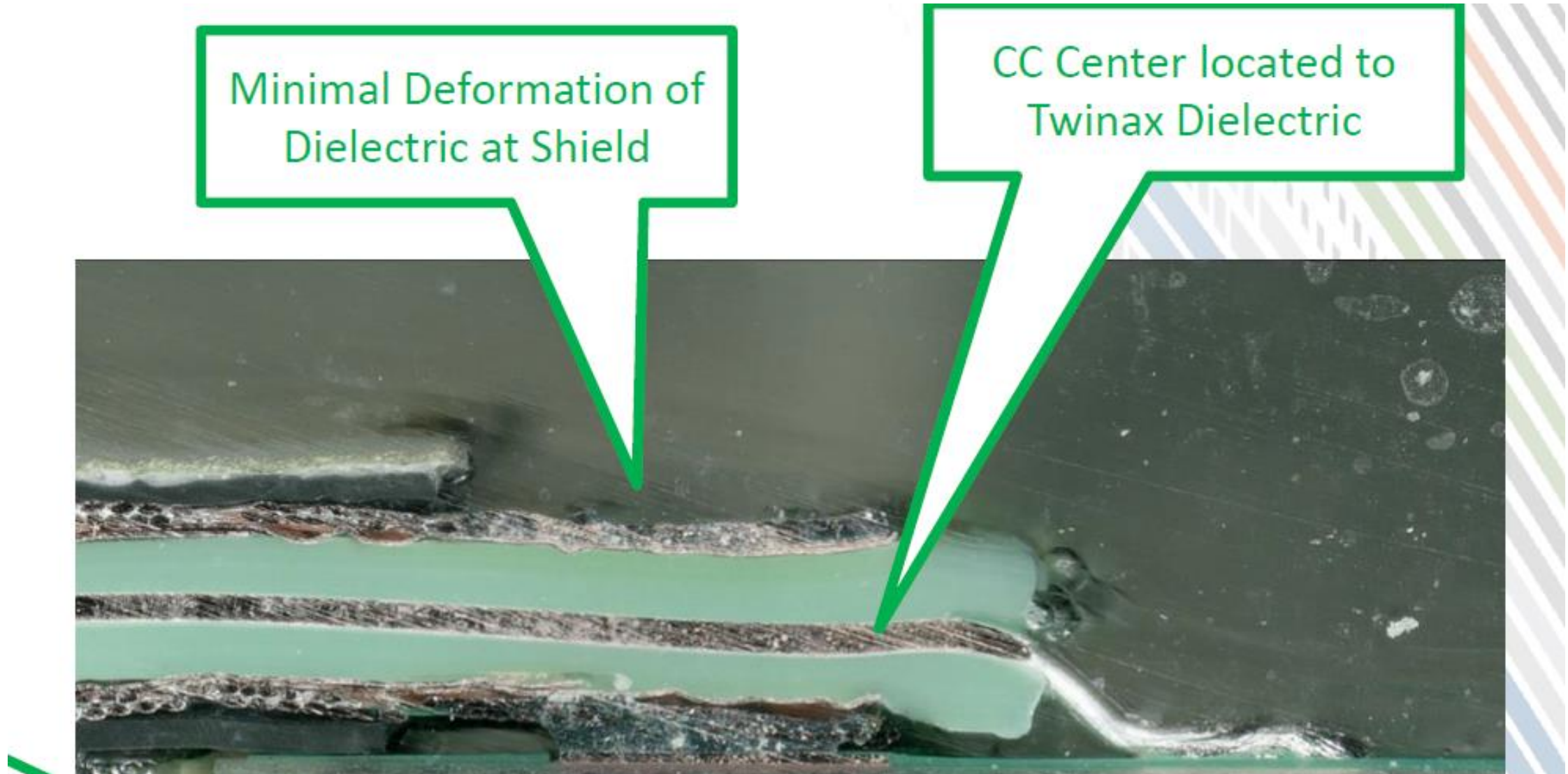
Data cables – A lot of work by the manufacturer to address the issue (courtesy by Samtec)

- Use of Bismuth soldering (lower temperature, and compliant with CERN safety rules).
- Pre-forming the cable end before soldering to counter-act the plastic deformation.
- Use of newly-developed low-pressure fixtures to partially relieve the mechanical strain on the dielectric during the soldering process.
- All validated for production



Data cables – Issue solved, ready for production (courtesy by Samtec)

Image here showing a pre-production cable obtained with the full production toolset (no prototype!)

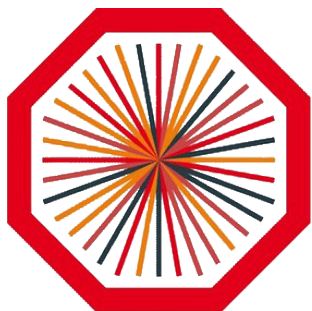


Data Cables – Production schedule

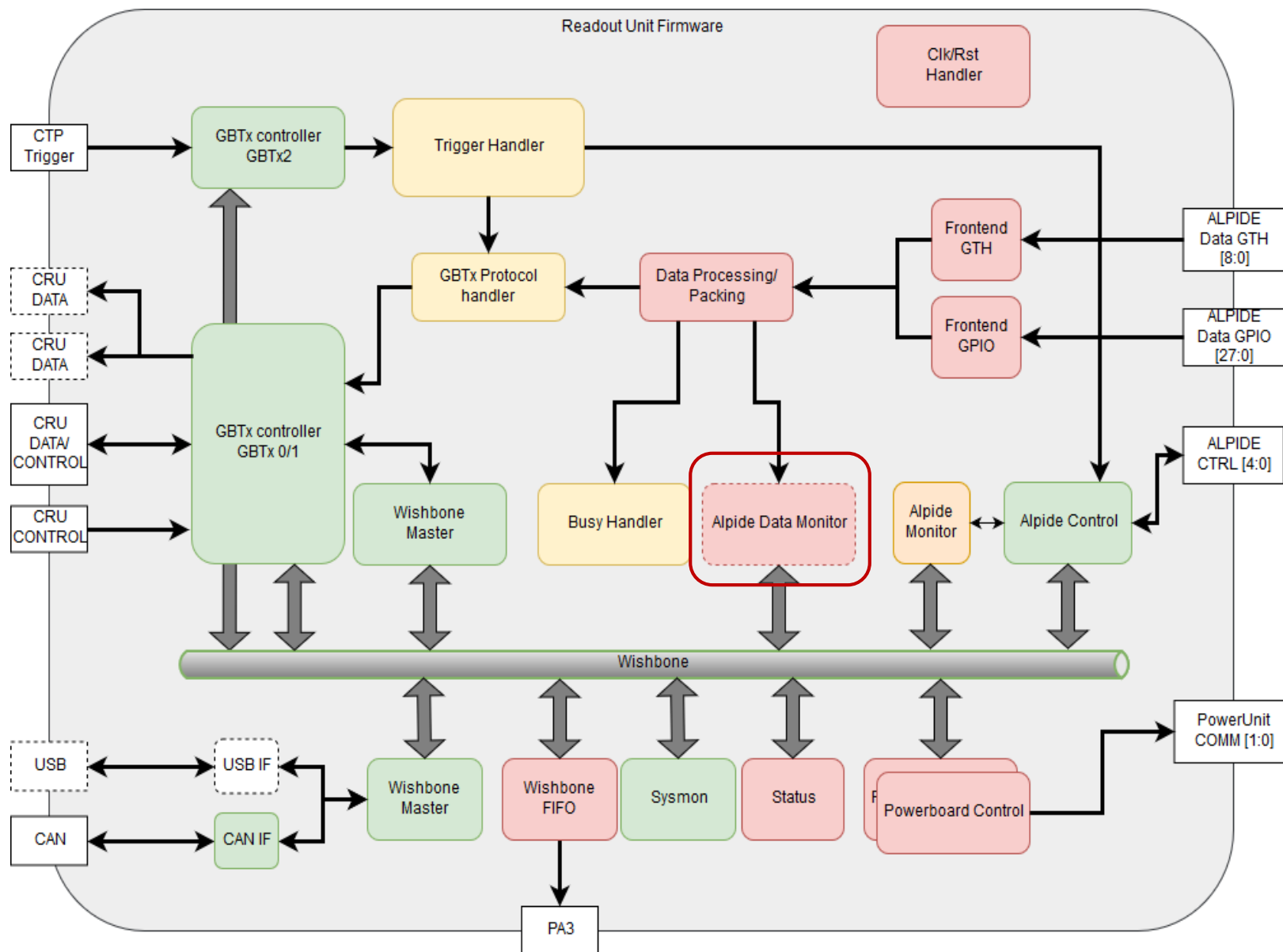
- Company confirmed production scheduled.
- Still on track to get 24 assemblies (48 cables) before Christmas break.

Production schedule (confirmed)

Phase		Qty	Week	Due
Purchase Order	T0		39	26 Sep 2018
Batch 1a production	T0 + 8w	24 A + B	47	15 Dec 2018
Batch 1b production	T0 + 12w	46 A + B	5	1 Feb 2019
Batch 2 production	T1 + 20w	90 A + B	10	8 Mar 2019
Batch 3 production	T1 + 26w	90 A + B	15	12 Apr 2019
Batch 1 production	T1 + 32w	90 A + B	19	08 May 2019



Firmware, software & CRU/O2 interaction



- Several minor changes have been done to the firmware in the last month.
- These are mainly tweaks and adjustments and not complete redesigns
- The most significant update is the addition of an Alpede monitor module.
- Still being specified – design expected to start by end of November
- A similar module for monitoring of the power board is being considered
- Not focused on push architecture (but might be considered for later).

- **Task:** Read I, V, T ++ from ALPIDEs during operation
- **Challenge:** Using ALPIDE control bus - shared with trigger distribution
- Specs (short form):
 - Support 3 modes of operation:
 - Idle mode
 - Continuous mode
 - Triggered mode (most challenging)
 - Deterministic timing for ALPIDE control bus access
 - Flexible solution with user specified ALPIDE registers to monitor
 - Monitored values available via Wishbone bus for *pulled* DCS access
 - Should also be easily adaptable for push mechanisms
- **Solution:** using the **abort gap** to readout ALPIDE parameters
 - In the worst case 2625 ns needed, 2975 ns is the abort gap duration.
 - Flexible solution with user specified ALPIDE registers to monitor
 - CTP issues a specific flag to signal the abort gap start (or we count by ourselves)

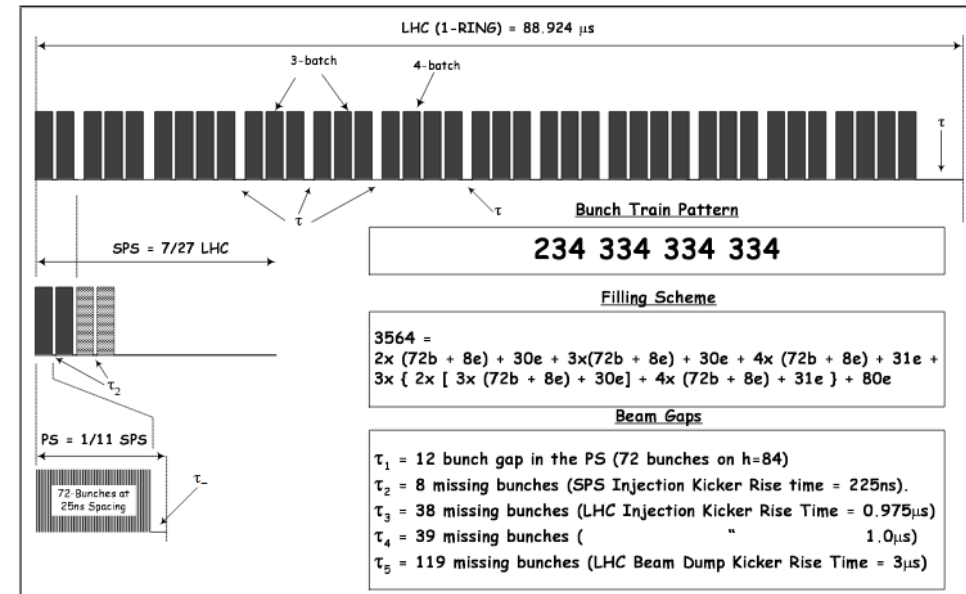
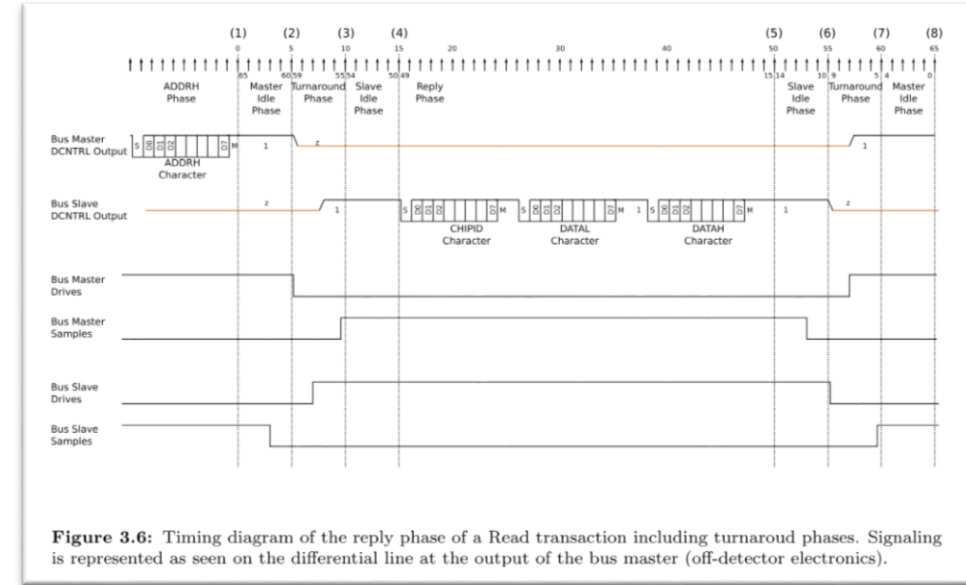


Figure 1: Schematic of the Bunch Disposition around an LHC Ring for the 25ns Filling Scheme

Programming of Xilinx

- Magnus is working on software control of the fifo interface in the XCKU as well as JTAG programming of the PA3
- Updating the scripts to support the PA3 v0206 firmware is on hold for now

Documentation

- An effort to improve (actually build!) the documentation on the XCKU project has been started.

Firmware updates:

- All 28 lanes enabled in the firmware
- The lane numbering has been remapped so it would be sequential on the new transition board for the RUV2

Software:

- SWT and SCA communication works
- However, only able to talk to one RU at the time due to limitations in CRU (see next slides)
- Data taking is working using the SW readout modules from O2



- **No major issues** so far.
- Excellent support from the CRU/O2 team.
- SWT protocol works as expected.

(Very) **minor issues**

- Python versions differ (some missed pre-agreement, little can be done now)
- ...

ITS specific requests (already in discussion)

- Some extra counters to better check the data flow (mostly to monitor SEE corruptions).
- **Multiple input FIFOs** (one per RU connected) to allow RU pushing SWT to the CRU.

CRU/O2 – ITS SWT on multiple channels (in discussion with O2/CRU)

SWT as present

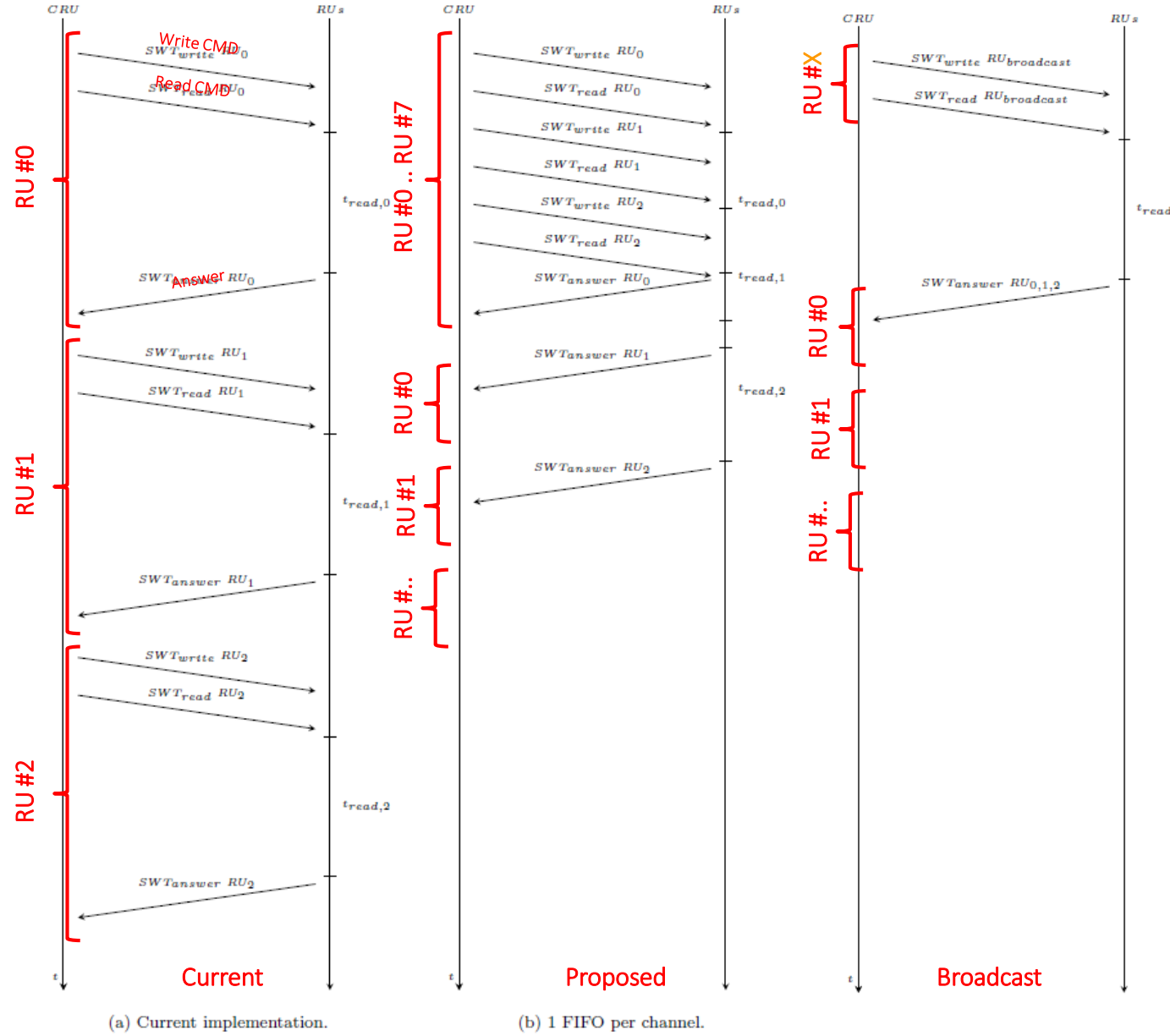
- Each Common Readout Unit (CRU) is connected to 8 Readout Units (RUs). Current CRU implementation has a multiplexer connecting to a single RU. **If a RU answers on a different channel than the one selected, the data are lost.**
- The answers for the SWT on a single RU can take “long time” for some operations, prompting for a “push” mechanism.

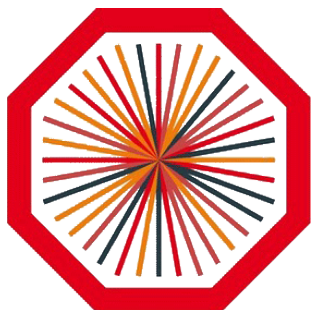
Uplink FIFOs on CRU

- What ITS proposes is a per-channel FIFO to store the results of the SWTs. This would greatly reduce the time to query information from multiple RUs.
- Each channel FIFO should have a depth of 1024 words.

CRU SWT broadcast

- If a per-channel FIFO is possible, it might be beneficial to broadcast the SWTs to different RUs.
- This would also greatly reduce the time required to execute periodic reads of the same values in different boards.
- This might also be done with a mask: instead of broadcasting to all the boards only a subset could be set with a 1-hot encoding.

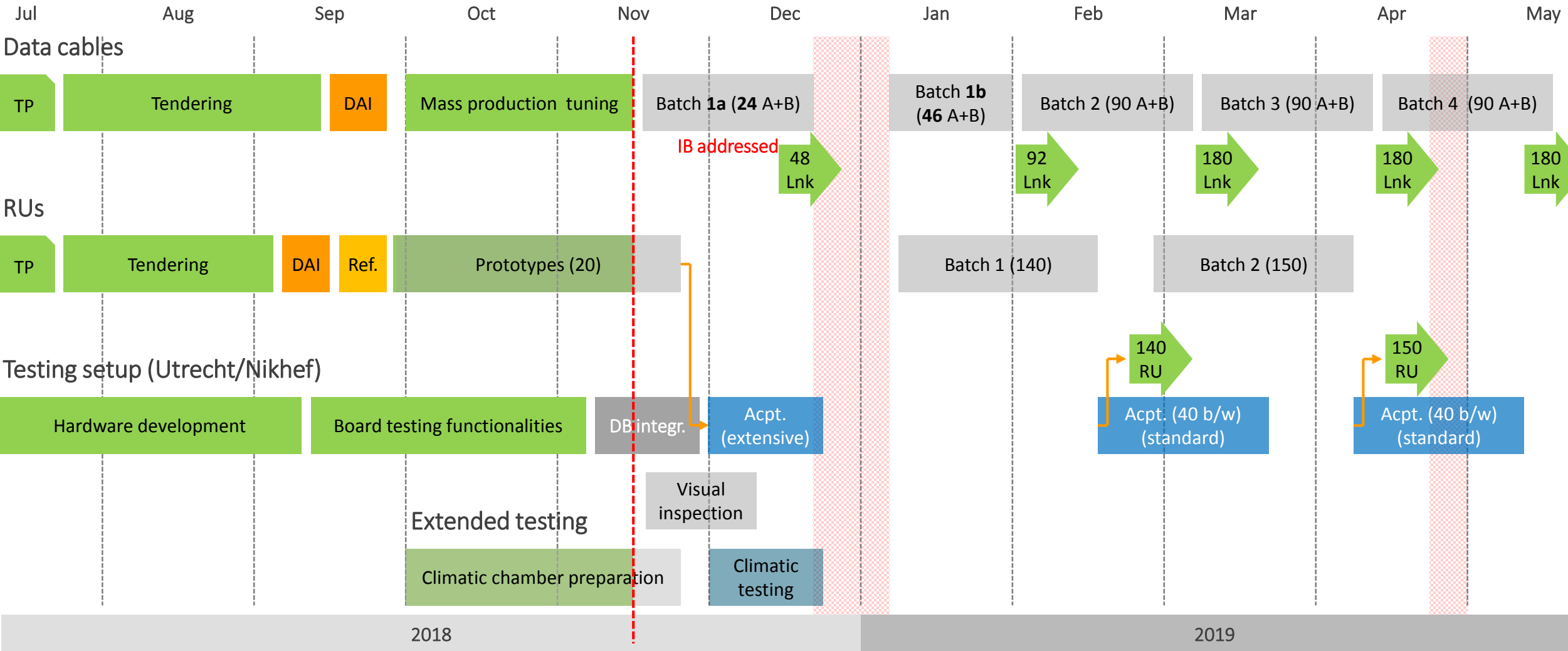




Timeline

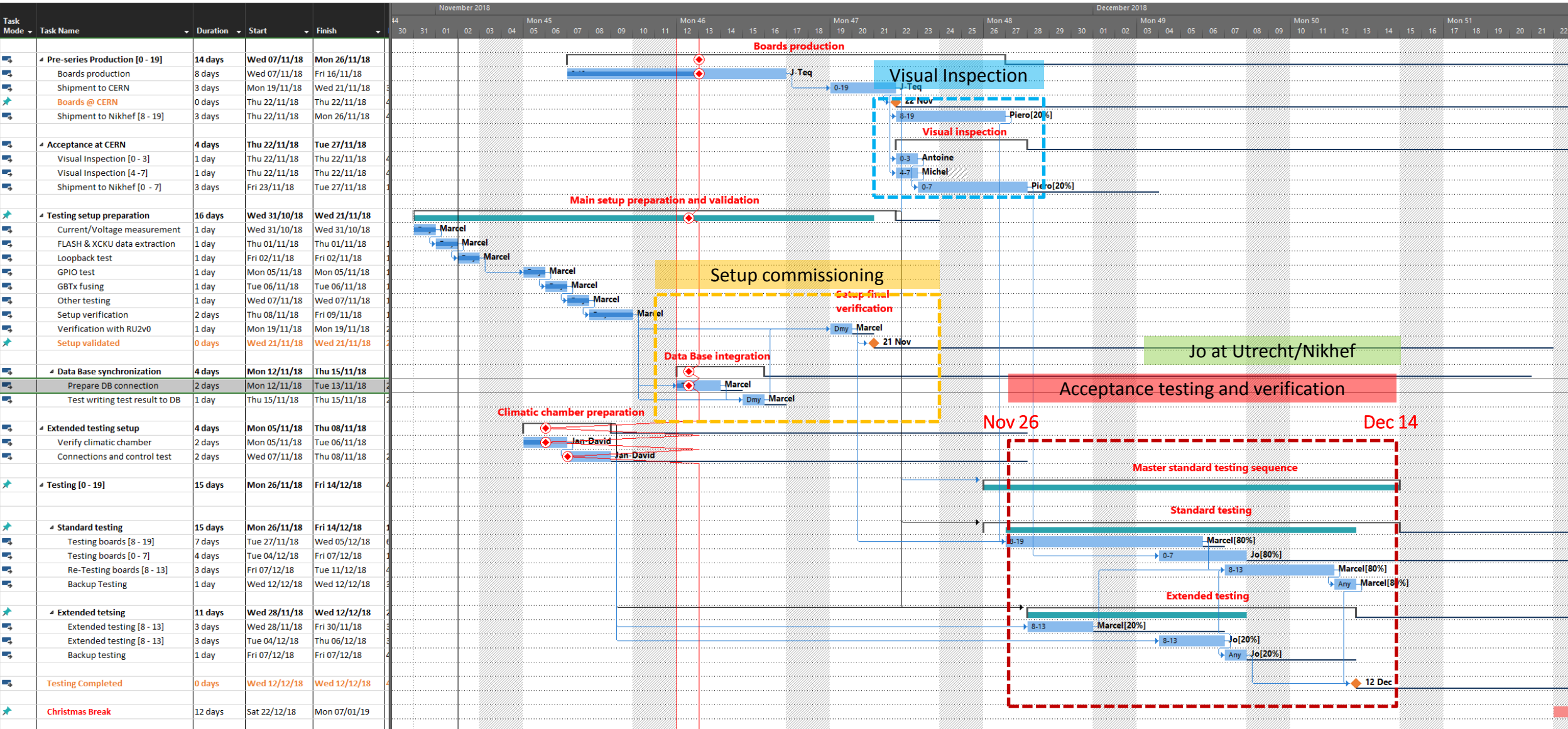
Production – Overall timeline

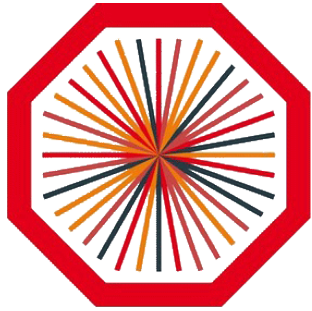
Both RUs and Data Cables are at the DAI. Goal is having 20 RUs before Christmas Break, as well as enough data cables to connect the whole IB (24 assemblies, equal to 40 data cables).



Production – RU2v1 pre-production testing detailed timeline

Setup and people almost ready in Utrecht/Nikhef to receive the 20 RU2v1 pre-production boards



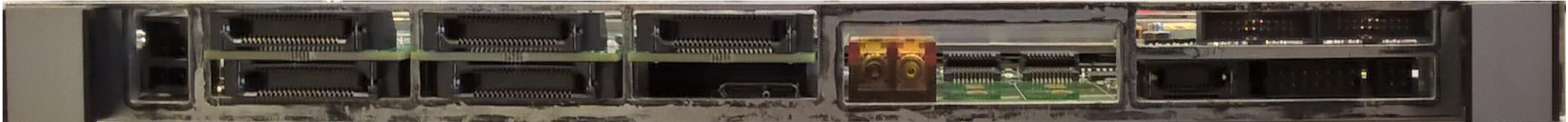


Backup

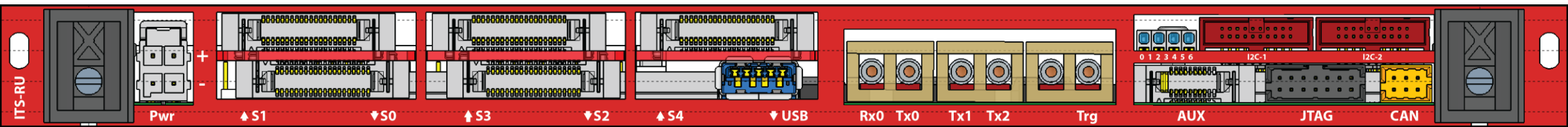
Readout Unit – Final front panel will be supplied together with the RUs

- Ancillary components and mounting hardware defined, ready to be ordered.

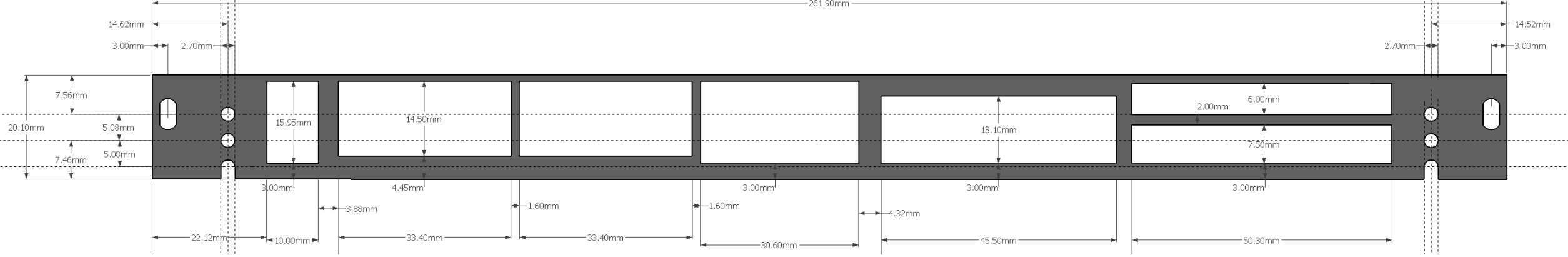
Prototype front panel



Serigraphy

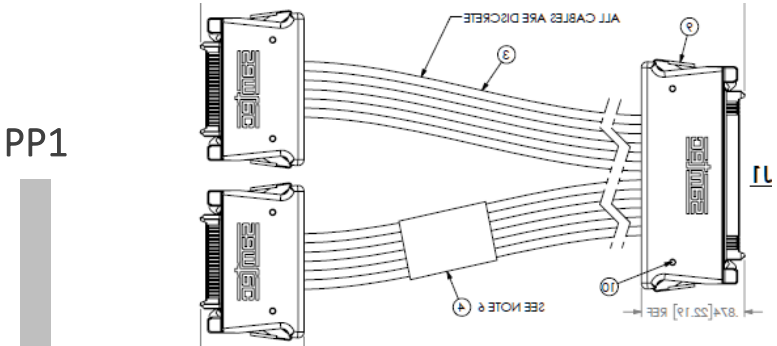


Technical drawing



Data Cables – Production summary

HDR-203194 (Type B)

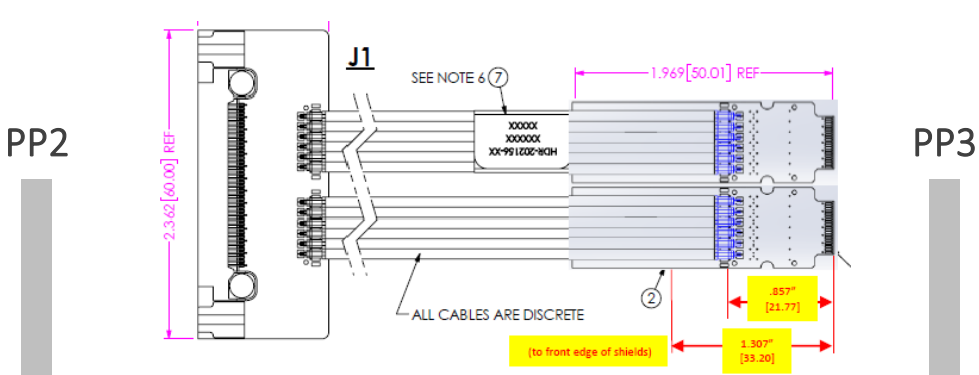


Production quantities

Layer	Qty	Length
3,4,5	60 + 8	4300 mm
0,1,2,3,4,5,6	156 + 8	4800 mm
0,1,2,6	72 + 8	5300 mm
	312 + 28	

340 Type B

HDR-206142 (Type A)



Production quantities

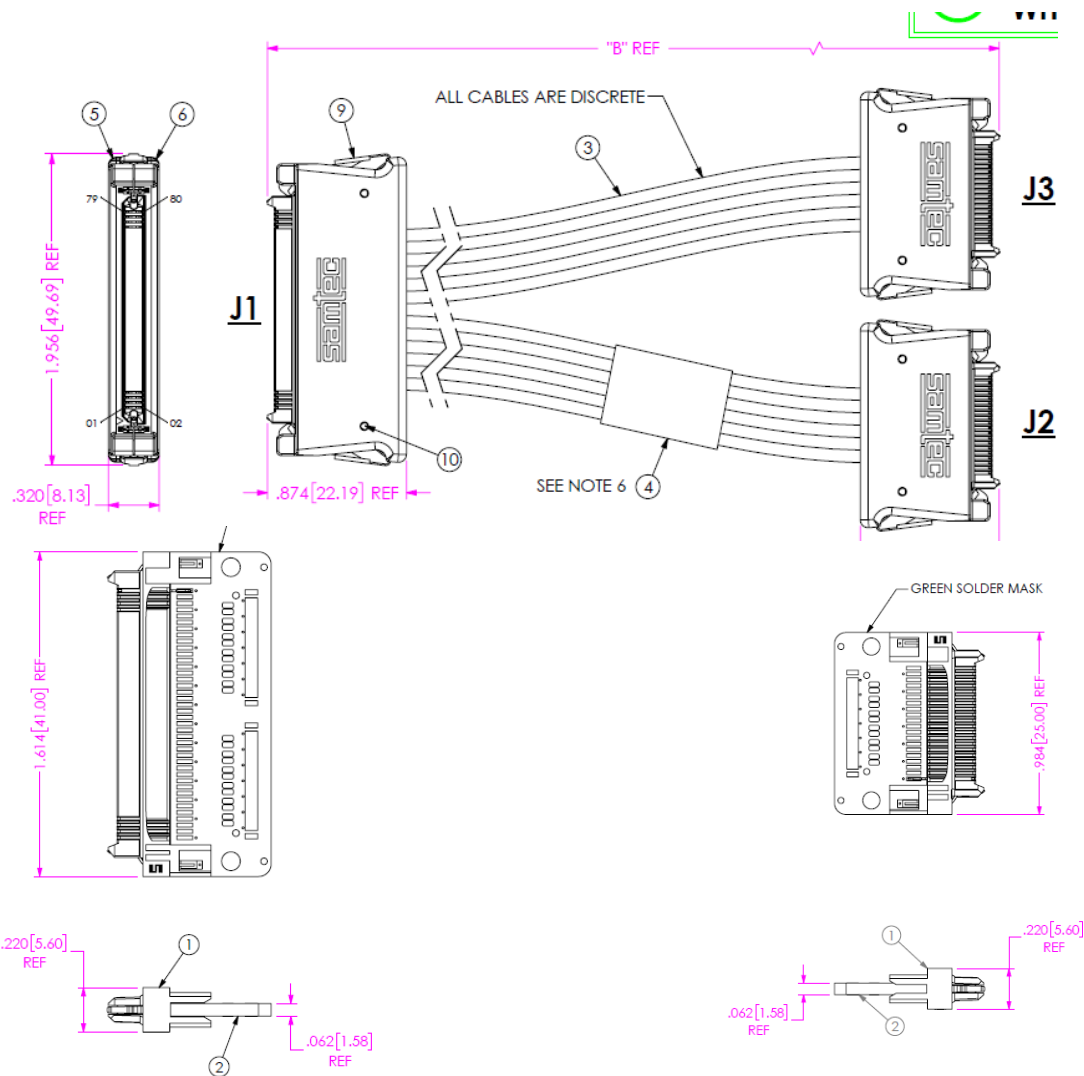
Layer	Qty	Length
5,6	180 + 8	2150 mm
3,4	108 + 8	2450 mm
0,1,2	24 + 8	2650 mm
	312 + 28	

340 Type A

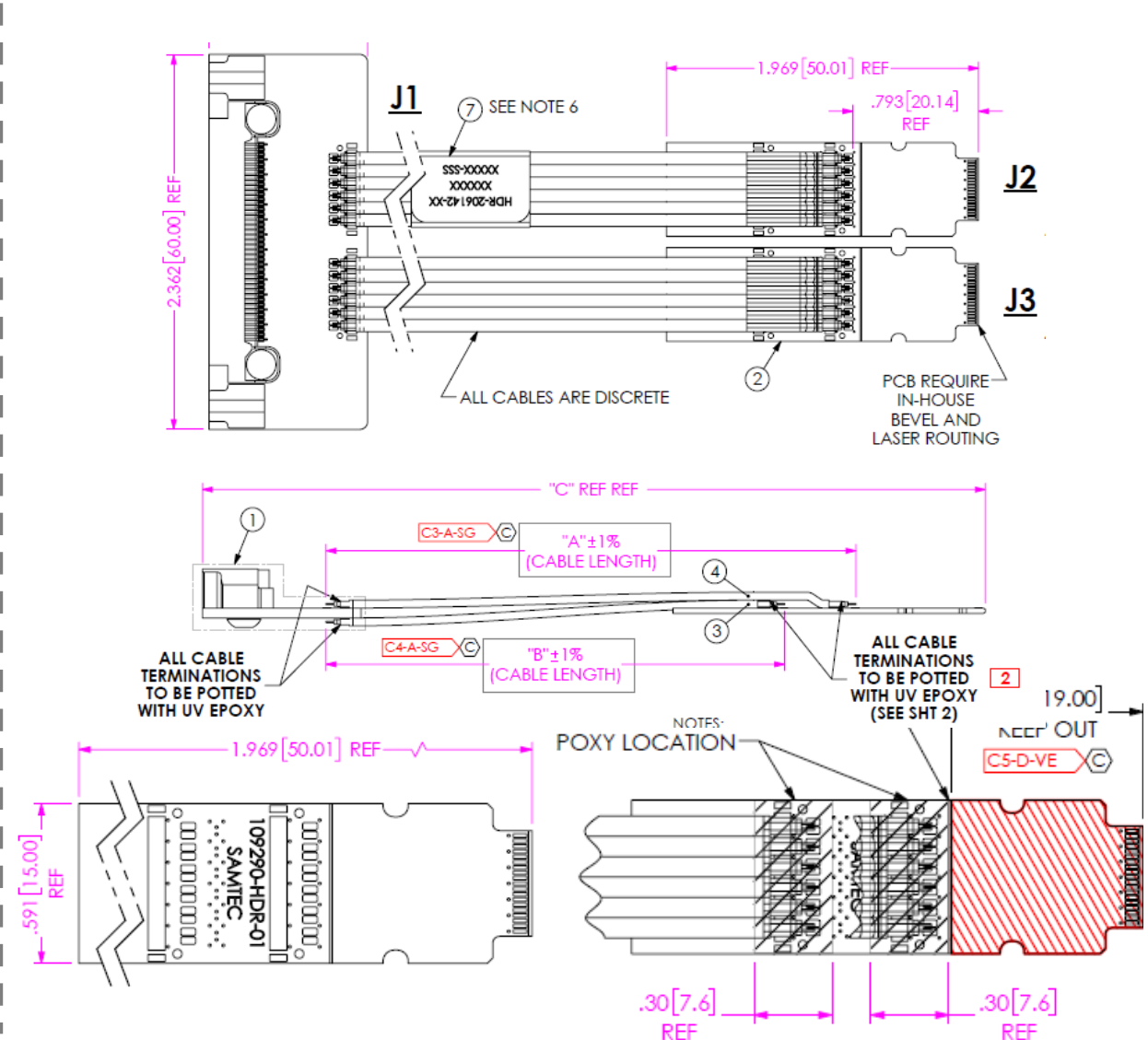
Data Cables – Design considered production ready

Considered the extensive testing so far, we will go for pre-production with latest version of drawings (12 Sep 2018)

HDR-203194 (Type B)



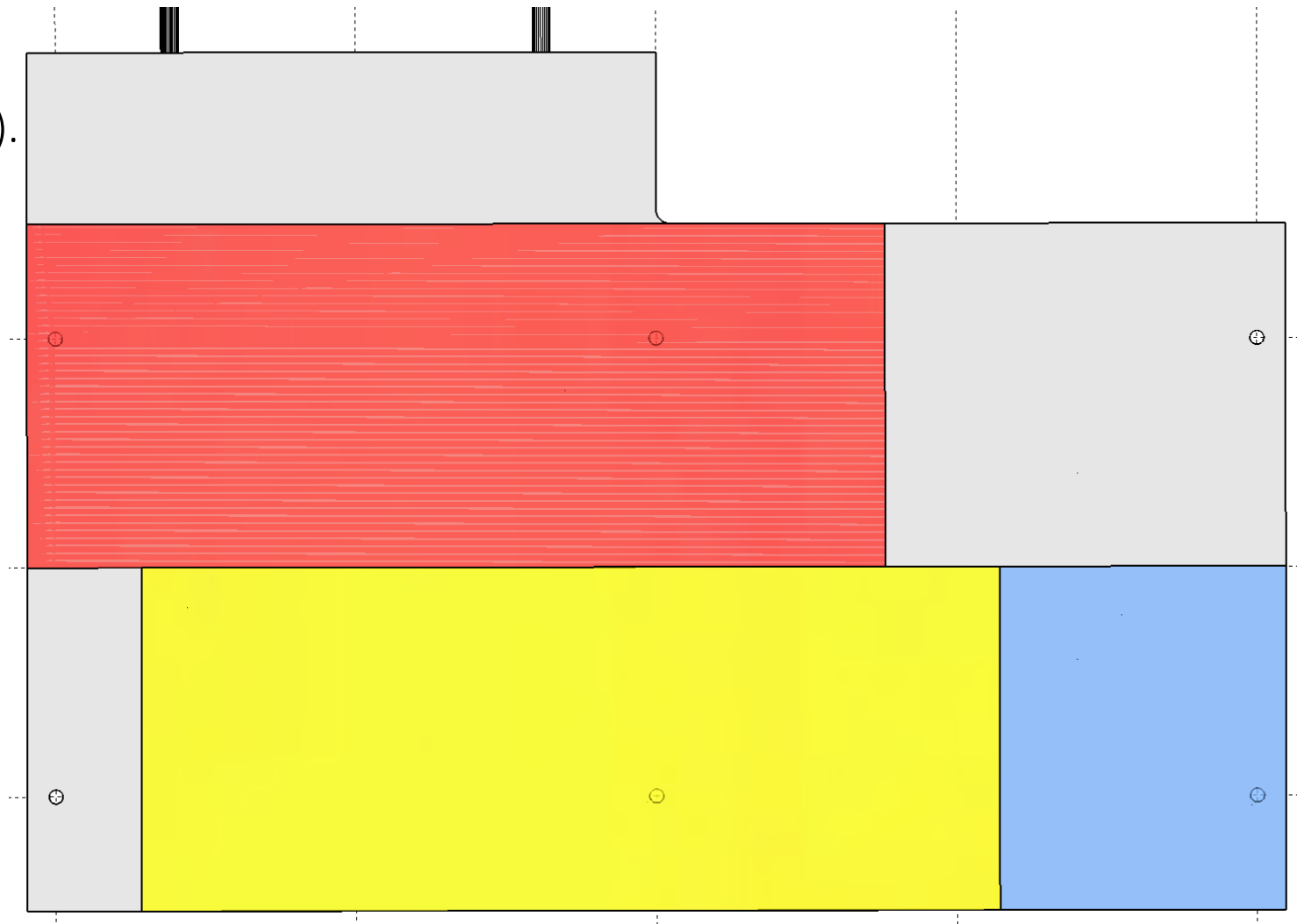
HDR-206142 (Type A)



Cold plate – Thermal padding

Three different thicknesses of thermal pad are necessary. For each thickness, cut a rectangular pad of the indicated dimensions. From a $150 \times 150 \text{ mm}^2$ mat, it is possible to make two 1mm thick pads, two 2mm thick pads and six 3mm thick pads.

- 1 mm thick: $150 \times 60 \text{ mm}^2$ (red in figure).
- 2 mm thick: $150 \times 60 \text{ mm}^2$ (yellow in figure).
- 3 mm thick: $50 \times 60 \text{ mm}^2$ (blue in figure).



- Procurement status:

- Quantity need (included spares) is 490:

- ITS RU: 220
- ITS PU: 180
- MFT : 90

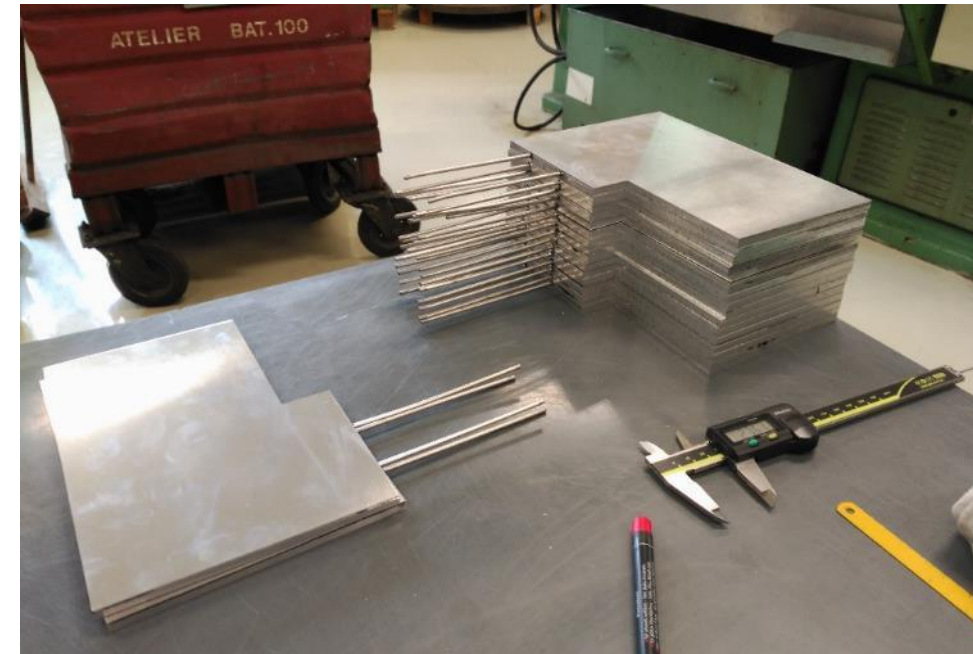
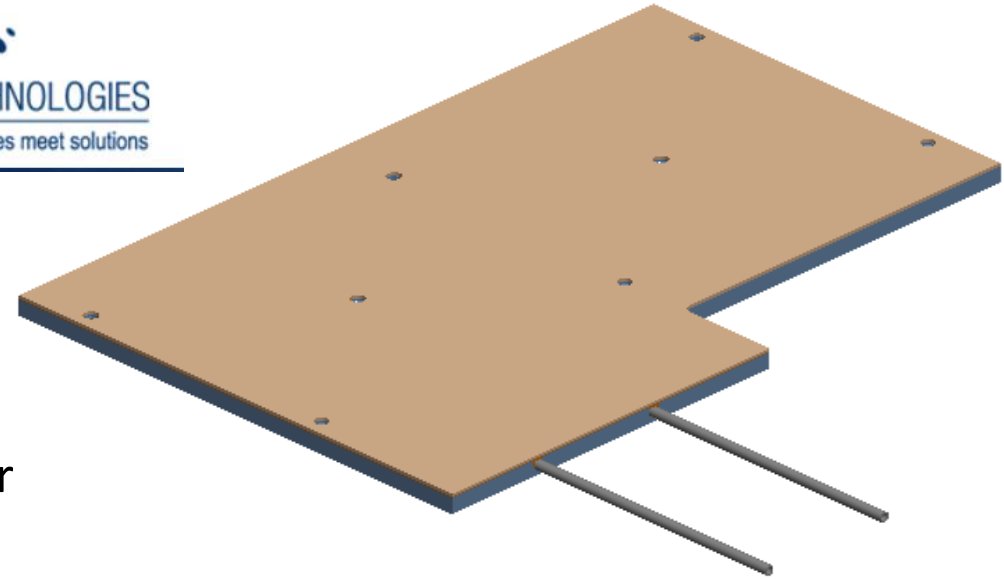
- Price Enquiry DO-31553/EP/ALICE in july with Purchase order sent out to AMS technologies

<https://edh.cern.ch/Document/SupplyChain/DAI/7316926>

- Delivery schedule:

- First lot of 40 units to be delivered directly to US **week 40**
- Remaining components (450) delivery: **week 44**

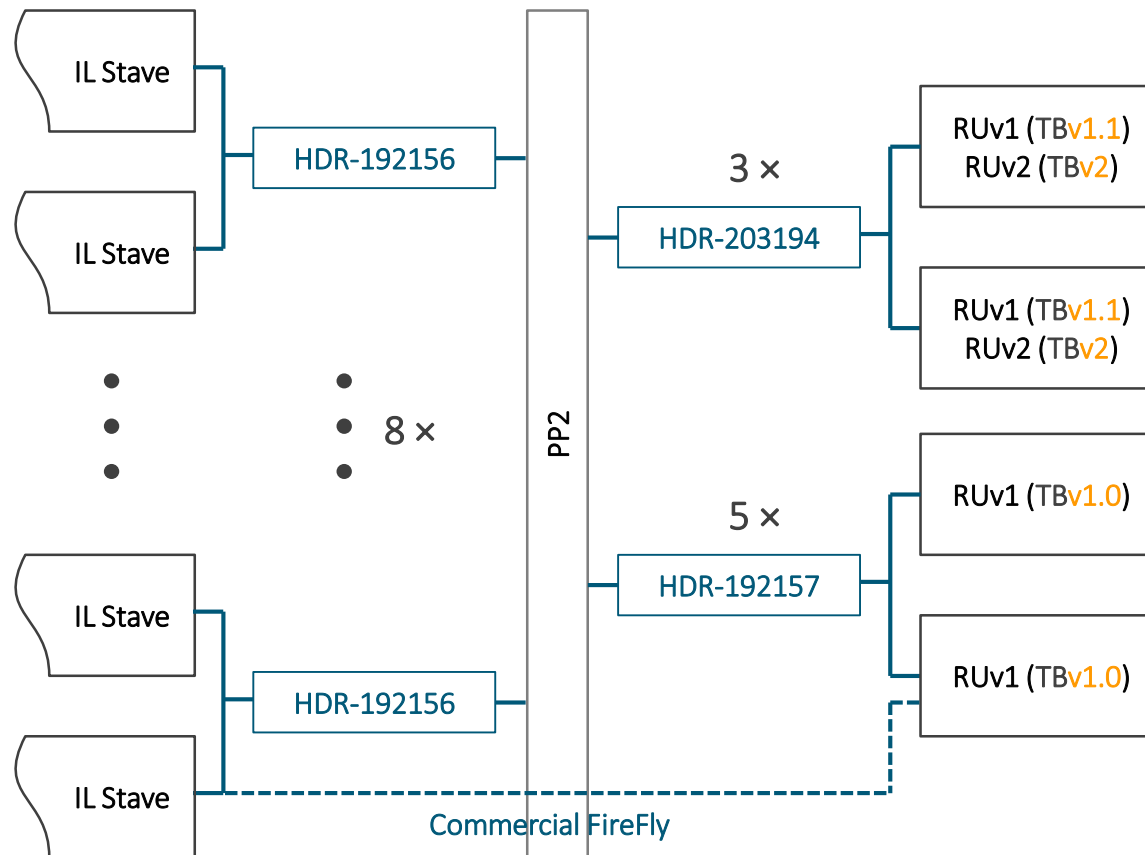
- N.24 units produced at CERN, can be delivered to US by the end of **week 35** (all plates produced, piping being cut to length and cleaned)



System – many transition boards flavors produced and in production

At the moment we have 8 PP2 to PP3 assemblies (HDR-192156), capable to connect 16 IB staves. From PP2 to PP3, we have prototype cables to connect:

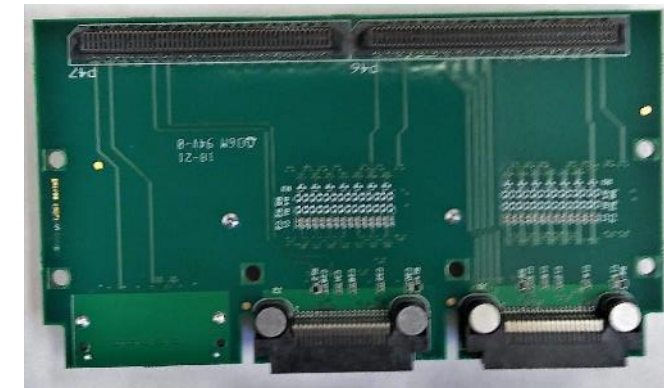
- Up to 16 RUv1 (likely 6-7 of them available for commissioning).
- Up to 6 RUv2, as they use the updated PP2 to PP1 data cable (HDR-203194)
- All PCBs necessary for “cavern” installation already produced, ready in Austin.



Transition Board v1.0 – compatible with RUv1.x and HDR-192157 cables (and commercial cables)



Transition Board v1.1 – compatible with RUv1.x and HDR-203194 cables



Transition Board v2 – compatible only with RUv2 and HDR-203194 cables